

| Gain Projects Passdown (Shanel, March 03, 2012) | To Whom | What Needed to Pass Down | Status |
|--|----------------------------|---|--------|
| 1) MOCVD tool procurement | | | |
| a. MOCVD facilities tender and preparation | WWZ | 1) Tender Documents and Explanation | |
| b. Ordering/lotting of MO sources | WWZ | 2) Determination of contractor for facilities Hook-Up | |
| c. (11) silicon wafer procurement | WWZ | 3) Oversight of hook-up preparation and process | |
| d. Interface with Veeco | WWZ | 1) Weizhu has already taken over much of this responsibility | |
| 2) GAN HEMT device fabrication planning and flow | WWZ | 1) Vendor contact for wafer procurement | |
| a. Runsheet generation | LKB, SHE | 2) Explanation of the wafers used for MOCVD growth | |
| b. Planning and tracking of fabrication modules | LKB, SHE | 1) Transition communication responsibility to Weizhu | |
| c. Lot running | LKB, SHE | 1) Process flow | |
| d. Recipe documentation | YL, SHE, LKB | 2) Runsheets currently generated | |
| 3) Rolls Royce Project | PL | 3) Understanding of tools involved | |
| a. Project leadership and planning | PL | 4) Understanding of module engineers | |
| b. GAN power device report | PL | 1) Gantt chart schedule | |
| c. Power device simulations | YL and Ravinder Singh | 1) Team up with NanopE staff to start running lots | |
| 4) Huawei Characterization Project | SHF (try to wrap this) | 1) Team members need to continue work with FAB staff to look at recipes on specific tools | |
| a. Characterization and modeling of Balun | SHF | 1) Project Scope and Deliverables | |
| b. Load Puller/High power device | SHF | 1) Power device report outline | |
| c. Characterization of 1.2V device at high DC VLB | YL | 2) Responsibilities of Team Members for parts of the report | |
| 5) GAN-on-Si Demo wafers | | 3) Current draft of report parts | |
| a. Inventory details | ST to WWZ | 1) Make sure YL and Ravinder have clear plan for simulations | |
| b. Import permit and declaration | ST to WWZ | 1) Work with Hou Debin to figure out demapping procedure | |
| 5) GAN PDK | Yan LI | 1) Work with Li Yihu to learn procedure for taking load pull measurement | |
| a. Project PI | Yuan LI if interested | 1) Work with Calvin Chua to learn how to do this characterization with temperature adjustable stage | |
| b. Power device analyzer/tender/procurement | Yuan LI, Lawrence Salvarai | 1) Inventory Documentation | |
| c. Pulsed IV equipment tender/procurement | Hailong Sun | 2) Explanation of growth structures | |
| d. Planning of PDK development with software | YL | 1) Import permit documents | |
| e. Interface with NTU team for CMOS compatible YL/Lawrence | YL/Hailong Sun | 2) Explanation of procedure for further import of new wafers/substrate carriers | |
| f. Management of load pull system | YL/Hailong Sun | 1) Documentation | |
| | | 2) Budget | |
| | | 3) Deliverables | |
| | | 4) Original Schedule | |
| | | 5) Supervision of Li Yihu | |
| | | 1) Tender Documents | |
| | | 2) Determination of vendor after tender response | |
| | | 1) Tender Documents | |
| | | 2) Determination of vendor after tender response | |
| | | 1) Contacts from Aquilino, Silvano | |
| | | 1) Set up meeting with NTU team | |
| | | 1) Set up meeting with Yihu to discuss the machine procedures | |